

# 2SK2933

# Silicon N Channel MOS FET High Speed Power Switching

REJ03G1047-0400

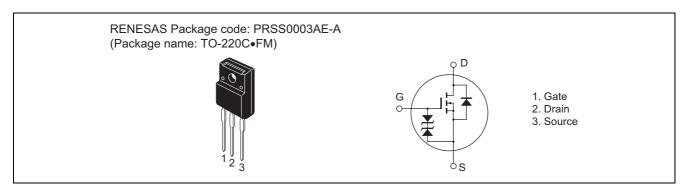
(Previous: ADE-208-556B)

Rev.4.00 Sep 07, 2005

### **Features**

- Low on-resistance  $R_{DS(on)} = 0.040 \; \Omega \; typ. \label{eq:DS_DS}$
- 4 V gate drive devices.
- High speed switching

## **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

| Item                                   | Symbol                      | Ratings     | Unit |
|--|-----------------------------|-------------|------|
| Drain to source voltage                | V <sub>DSS</sub>            | 60          | V    |
| Gate to source voltage                 | $V_{GSS}$                   | ±20         | V    |
| Drain current                          | I <sub>D</sub>              | 15          | A    |
| Drain peak current                     | I <sub>D(pulse)</sub> Note1 | 60          | Α    |
| Body-drain diode reverse drain current | I <sub>DR</sub>             | 15          | А    |
| Avalanche current                      | I <sub>AP</sub> Note3       | 15          | А    |
| Avalanche energy                       | E <sub>AR</sub> Note3       | 19          | mJ   |
| Channel dissipation                    | Pch Note2                   | 25          | W    |
| Channel temperature                    | Tch                         | 150         | °C   |
| Storage temperature                    | Tstg                        | -55 to +150 | °C   |

Notes: 1. PW  $\leq$  10 $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Ta = 25°C

3. Value at Tch = 25°C, Rg  $\geq$  50  $\Omega$ 

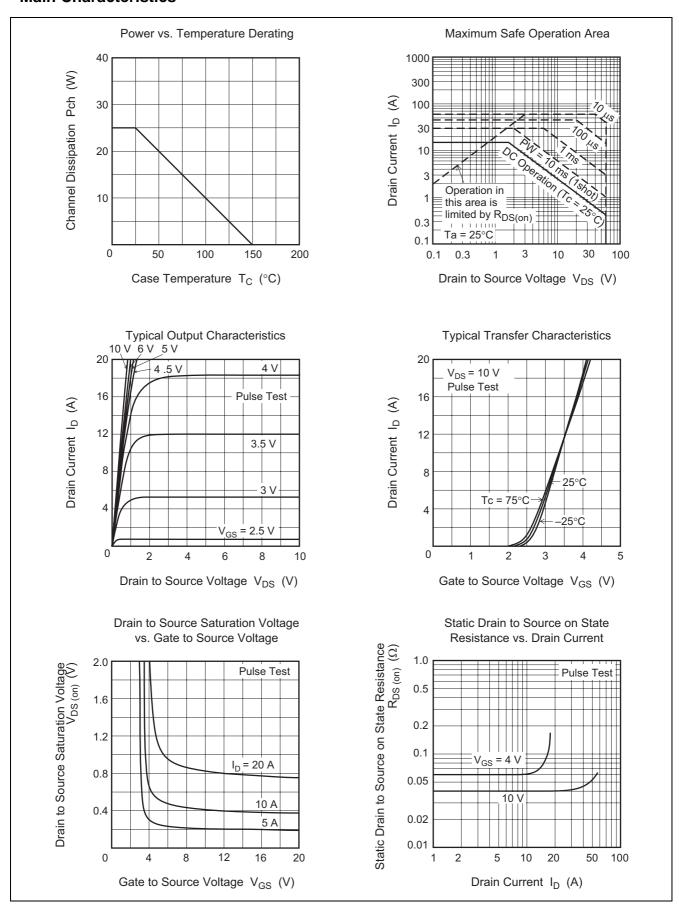
# **Electrical Characteristics**

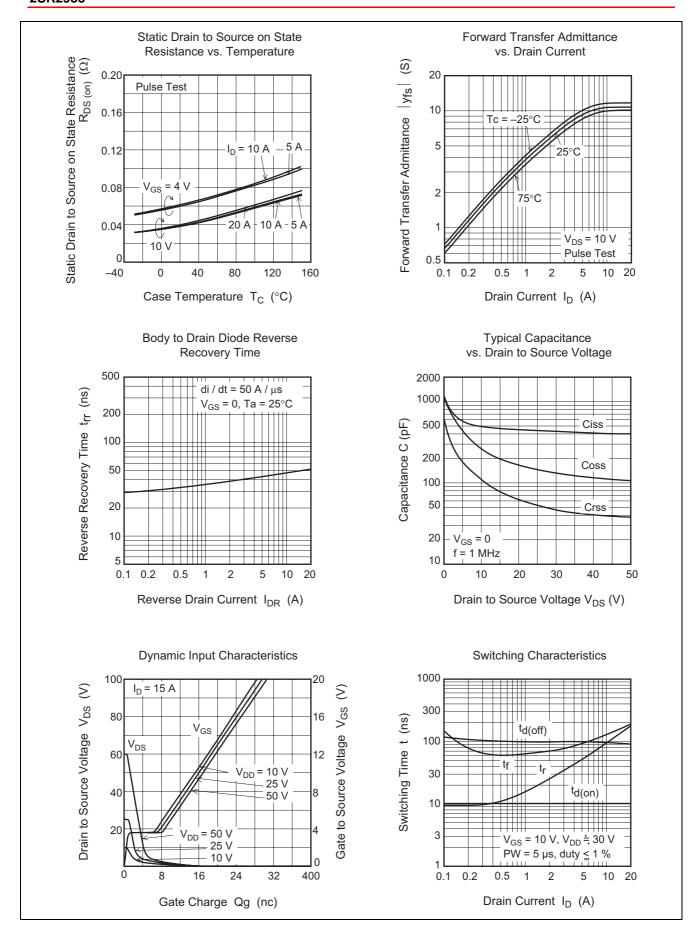
 $(Ta = 25^{\circ}C)$ 

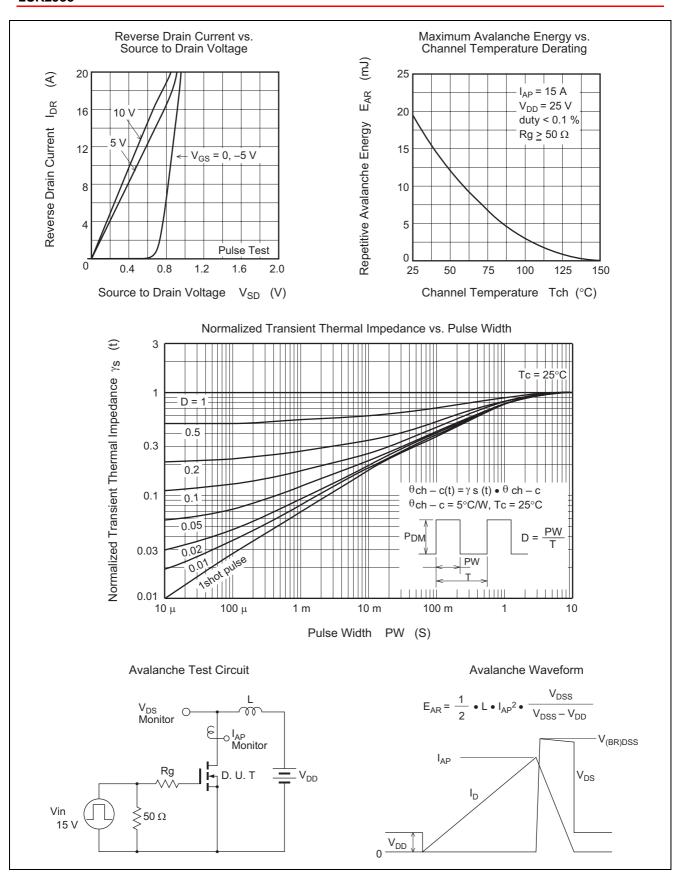
| Item                                   | Symbol              | Min | Тур   | Max   | Unit | Test Conditions   |  |
|--|---------------------|-----|-------|-------|------|---|--|
| Drain to source breakdown voltage      | $V_{(BR)DSS}$       | 60  | _     | _     | V    | $I_D = 10 \text{ mA}, V_{GS} = 0$   |  |
| Gate to source breakdown voltage       | $V_{(BR)GSS}$       | ±20 | _     | _     | V    | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$                                     |  |
| Zero gate voltage drain current        | I <sub>DSS</sub>    | _   | _     | 10    | μΑ   | $V_{DS} = 60 \text{ V}, V_{GS} = 0$                                       |  |
| Gate to source leak current            | $I_{GSS}$           | _   | _     | ±10   | μΑ   | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$                                   |  |
| Gate to source cutoff voltage          | $V_{GS(off)}$       | 1.5 | _     | 2.5   | V    | $I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$                               |  |
| Static drain to source on state        | R <sub>DS(on)</sub> | _   | 0.040 | 0.052 | Ω    | $I_D = 8 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$                 |  |
| resistance                             | R <sub>DS(on)</sub> | _   | 0.060 | 0.105 | Ω    | $I_D = 8 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note4}}$                  |  |
| Forward transfer admittance            | y <sub>fs</sub>     | 7   | 11    | _     | S    | $I_D = 8 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$                 |  |
| Input capacitance                      | Ciss                | _   | 500   | _     | pF   | $V_{DS} = 10 \text{ V}, V_{GS} = 0,$                                      |  |
| Output capacitance                     | Coss                | _   | 260   | _     | pF   | f = 1 MHz   |  |
| Reverse transfer capacitance           | Crss                | _   | 110   | _     | pF   |   |  |
| Turn-on delay time                     | t <sub>d(on)</sub>  | _   | 10    | _     | ns   | $V_{GS} = 10 \text{ V}, I_D = 8 \text{ A},$                               |  |
| Rise time                              | t <sub>r</sub>      | _   | 80    | _     | ns   | $R_L = 3.75 \Omega$   |  |
| Turn-off delay time                    | t <sub>d(off)</sub> | _   | 100   | _     | ns   |   |  |
| Fall time                              | t <sub>f</sub>      |     | 110   | _     | ns   |   |  |
| Body-drain diode forward voltage       | $V_{DF}$            | _   | 0.9   | _     | V    | $I_F = 15 \text{ A}, V_{GS} = 0$  |  |
| Body–drain diode reverse recovery time | t <sub>rr</sub>     | _   | 50    | _     | ns   | $I_F = 15 \text{ A}, V_{GS} = 0$<br>$di_F/dt = 50 \text{ A}/\mu \text{s}$ |  |

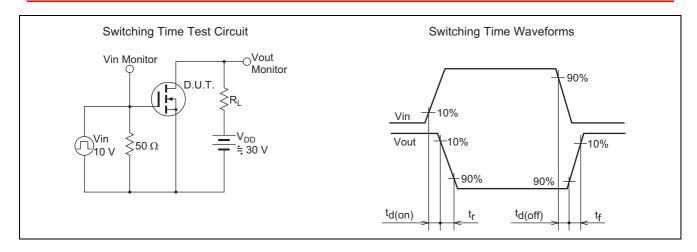
Note: 4. Pulse test

## **Main Characteristics**

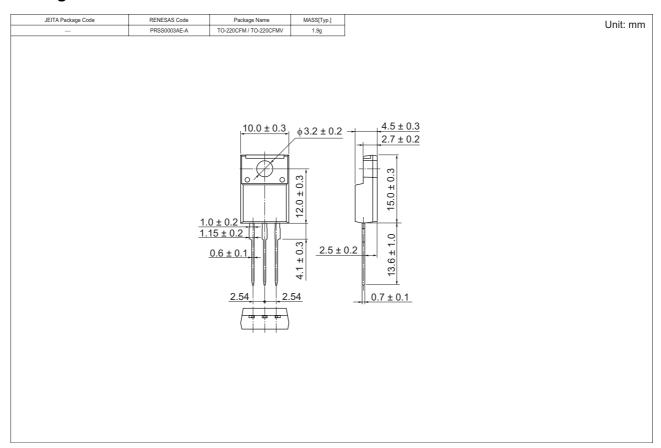








# **Package Dimensions**



# **Ordering Information**

| Part Name | Quantity | Shipping Container |
|-----------|----------|--------------------|
| 2SK2933-E | 600 pcs  | Box (Tube)         |

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